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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/750,489	12/31/2003	Ki-Min Lee	20059/PIA31071	1804	
34431	7590 07/08/2005		EXAMINER		
HANLEY, FLIGHT & ZIMMERMAN, LLC			LEE, CA	LEE, CALVIN	
20 N. WACKER DRIVE SUITE 4220		ART UNIT	PAPER NUMBER		
CHICAGO, IL 60606			2818		
			DATE MAILED: 07/08/2005		

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)				
Office Action Summary		10/750,489	LEE, KI-MIN				
		Examiner	Art Unit				
		Lee, Calvin	2818				
	The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply						
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely. - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).							
Status							
1)	Responsive to communication(s) filed on						
· —		action is non-final.					
3)							
	closed in accordance with the practice under $\boldsymbol{\mathcal{E}}$	Ex parte Quayle, 1935 C.D. 11, 45	33 O.G. 213.				
Disposition of Claims							
4)🛛	Claim(s) <u>1-15</u> is/are pending in the application.						
	4a) Of the above claim(s) is/are withdrawn from consideration.						
5)	Claim(s) is/are allowed.						
6)🛛	☑ Claim(s) <u>1,3-7 and 9-15</u> is/are rejected.						
•	7) Claim(s) <u>2 and 8</u> is/are objected to. 8) Claim(s) are subject to restriction and/or election requirement.						
8)□							
Applicati	on Papers	•					
9) The specification is objected to by the Examiner.							
10)🛛	10)⊠ The drawing(s) filed on <u>31 December 2003</u> is/are: a)⊠ accepted or b)□ objected to by the Examiner.						
	Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).						
:	Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).						
11)	11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.						
Priority u	ınder 35 U.S.C. § 119						
12)⊠ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).							
_	☑ All b)☐ Some * c)☐ None of:		·				
	1.⊠ Certified copies of the priority documents have been received.						
2. Certified copies of the priority documents have been received in Application No							
	3. Copies of the certified copies of the priority documents have been received in this National Stage						
	application from the International Burea	, , , , , , , , , , , , , , , , , , , ,					
* See the attached detailed Office action for a list of the certified copies not received.							
Attachmen	Mc)						
1) Notice of References Cited (PTO-892) 4) Interview Summary (PTO-413)							
2) Notic	e of Draftsperson's Patent Drawing Review (PTO-948)	Paper No(s)/Mail Da	ite				
	nation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) r No(s)/Mail Date	5) Notice of Informal P 6) Other:	atent Application (PTO-152)				

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OFFICE ACTION

Claim Rejections - 35 U.S.C. § 102

- 1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 (e) that form the basis for the rejections under this section made in this Office action:
- (e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.
- 2. Claims 1, 3-5, 7, 11-12, and 14-15 are rejected under 35 US.C 102(e) as being anticipated by *Rasmussen (US 2004/0262658)*.
- a) Rasmussen discloses a method of fabricating an MIM capacitor of high capacitance in a semiconductor device, the method comprising the steps of:
- -depositing an interlayer dielectric film 25 of PSG or TEOS on a metal line 52 [¶ 0039-0041]
- -planarizing the interlayer dielectric film [see the top surface of the dielectric film]
- -etching the dielectric film to form an MIM capacitor forming region 41 [Fig. 10]
- -sequentially depositing a lower electrode 71, an insulator layer 72, and an upper electrode 73 on the interlayer dielectric film; wherein the insulator layer comprises Ta₂O₅, Al₂O₃, Si₃N₄ [¶ 0043] and the upper electrode comprises ruthenium and platinum [¶ 0044].
- -etching the lower and upper electrodes, the insulator layer to form the MIM [Fig. 11]
- b) In re claims 9 and 10, *Rasmussen* suggests the interlayer dielectric layer being planarized by CMP or dry etch (i.e., etch back) [¶ 0043].
- 3. Claims 1, 3, 5-7, 9-10, and 12-13 are rejected under 35 US.C 102(e) as being anticipated by *Hackler et al (US 2005/0063140)*.
- a) Hackler et al discloses a method of fabricating an MIM capacitor of high capacitance in a semiconductor device, the method comprising the steps of:
- -depositing an interlayer dielectric film 120 of BPSG or TEOS on a metal line 130 [¶ 0025-0026]
- -inherently planarizing the interlayer dielectric film [see the top surface of the dielectric film 120]
- -etching the dielectric film to form an MIM capacitor forming region 135 [Fig. 2]

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-sequentially depositing a lower electrode 140, an insulator layer 150, and an upper electrode 160 on the interlayer dielectric film; wherein the lower electrode comprises Ti, W and TiN [\P 0029] and the insulator layer comprises Ta₂O₅, Al₂O₃ and Si₃N₄ [\P 0035].

-etching the lower and upper electrodes, the insulator layer to form the MIM [¶ 0059-0060]

b) In re claims 14 and 15, *Hackler et al* suggests the electrode stack being planarized by CMP or etch back [¶ 0054].

Allowable Subject Matter

4. Claims 2 and 8 are objected to as being dependent upon rejected claims, but would be allowable if rewritten in independent form including all of the limitations of the base claims and any intervening claims. Neither *Rasmussen* nor *Hackler et al* teaches or suggests a capacitance of the MIM capacitor being determined by controlling a thickness of the interlayer dielectric layer.

Contact Information

5. Any inquiry concerning this communication from the Examiner should be directed to Calvin Lee at (571) 272-1896 on Mondays thru Thursdays 6:30-4:30PM. If attempts to reach the examiner by telephone are unsuccessful, Art Unit 2818's Supervisory Patent Examiner David Nelms can be reached at (571) 272-1787. The fax phone number for the organization (where this application is assigned to) is (703) 872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system at http://pair-direct.uspto.gov. Should you have questions on access to the PAIR system, contact the Electronic Business Center at (866) 217-9197.

David Nelms

Supervisory Patent Examiner Technology Center 2800

Date: June 30, 2005